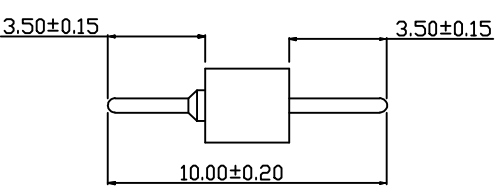
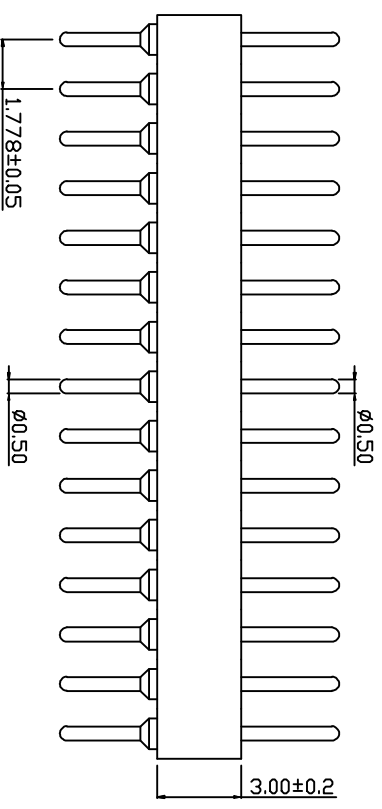
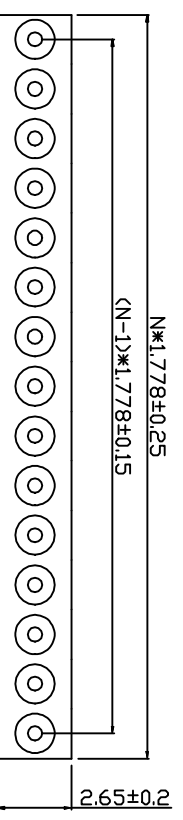


HSE ROHS

REV	ECN NO	DESCRIPTION	DATE	NAME
A		NEW		



Ordering Information

L489XX - X X XX X

NO. of Pins Per Row: 01-40P
 The connection method: 0=180° 1=90° 2=SMT
 Contact Plating: 1=Gold Flash 2=Au/Tin
 Serial NO.: 01-99
 Packing: A=PE Bag B=Tube C=Tray D=Reel

STANDARD TOLERANCE (EXCEPT SPECIFIED)	LINER	ANGLES
.0 ±0.30	0.°	±3°
.00 ±0.20	.0°	±2°
.000 ±0.10	.00°	±1°

LDCONN 东莞连大精密制品有限公司		Dongguan Lianda Precision Products Co., LTD	
TITLE	Drawn by	Lu Junhui	18.11.12
PART NO	Checked by		
DRAWING NO	APPROVED BY		
SCALE	UNIT	PAGE	SIZE
1:1	mm	1/1	A4

Materials
 Pin (outer sleeve):3mm, machined, CuZn39Pb2
 Chip/contact finger:3mm,alum copper/heat treated
 Pin(contact sleeve):
 Tin plated :2μmNi80μmnickel,5umZn0.17μm
 Gold plated:2μmNi80μmnickel,full gold
 Plating application:2umNi80 μmnickel,gold or tin plating
 Insulator body:heat-stable filled thermoplastic polymer UL94V-0

Electrical
 Current rating:3 Amp/contact max.
 Contact resistance:≤ 4m Ω/contact
 Insulation resistance:≥ 1000M Ω at V=100V
 Operating voltage:80 AC/DC

Mechanical
 Operating temperature :Gold plated:-55g to +105g
 (Conformal) -57g to +105g
 Tin plated:-40g to +105g
 Average insertion force with steel pin of 0.45mmφ0.17 < 200g
 Average withdrawal force with steel pin of 0.45mmφ0.17 > 50g
 Mechanical lifespan:200
 Soldering temperature:260 g , 10s max

Application
 1.The open frame is most common type.
 2.The open body design gives better access for cleaning and inspections) to air -cooling.
 3.Side and end stable.
 4.High retention design prevents IC without during heavy vibration.
 5.Closed bottom sleeve for 100% anti-wicking of solder.
 6.Thick free construction.

Solderability(IEC 68-2-64 Ta)≥200g , 5s Max
 Resistance to soldering heat(IEC 68-2-20 Tb)≥200g , 5s Max